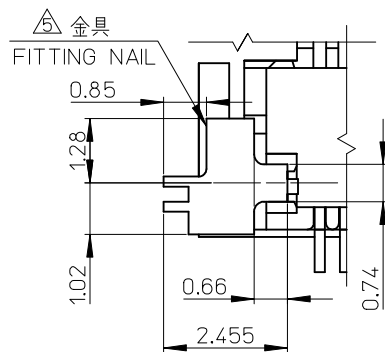
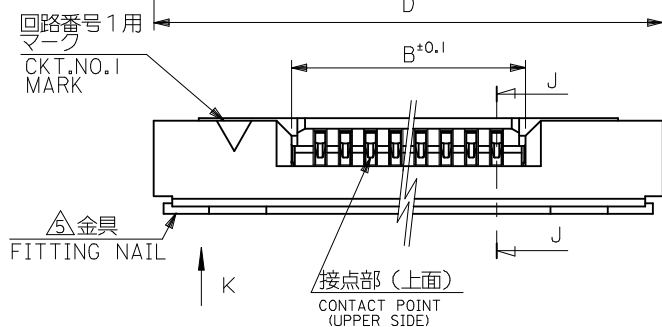
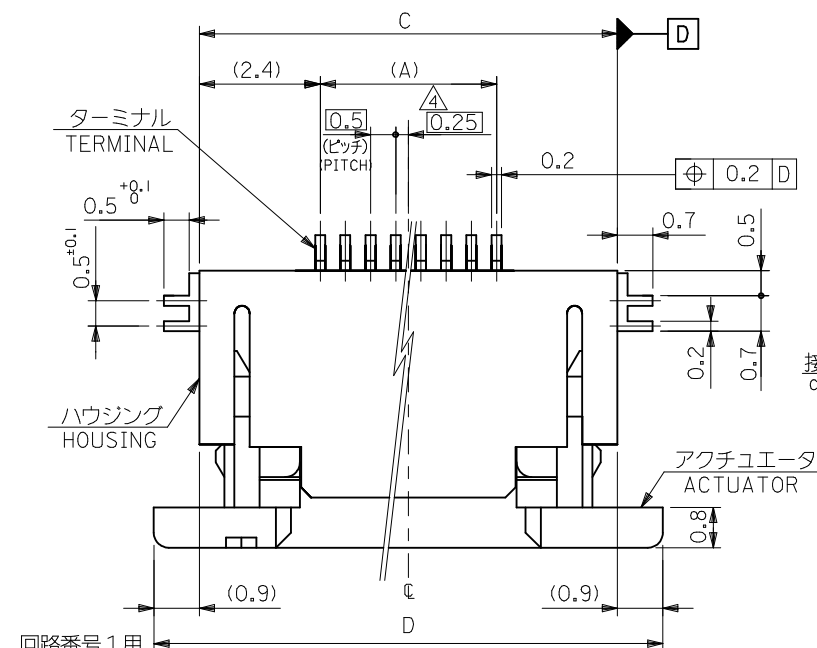
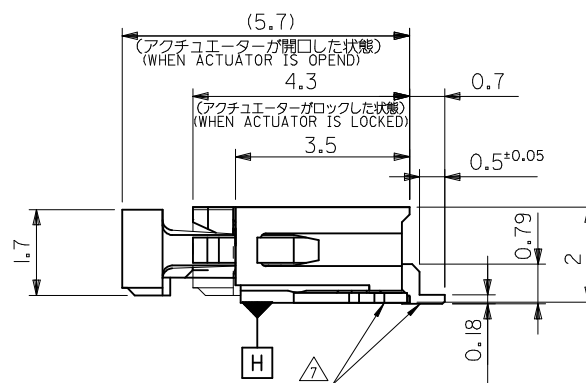
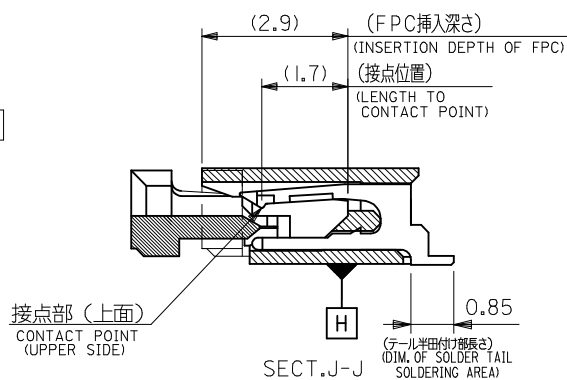




VIEW K
(金具部投影図)
(DETAIL OF FITTING NAIL)

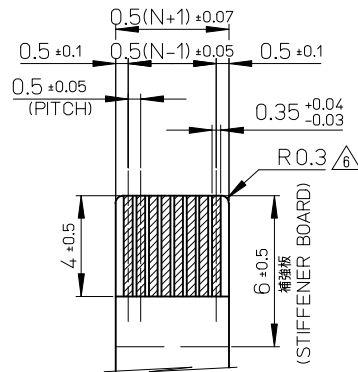


1. 使用材料
 MATERIAL
 ハウジング：ポリアミド(PA)、ガラス充填、UL94V-0、ナチュラル(白)
 HOUSING: POLYAMIDE, GLASS FILLED, UL94V-0, NATURAL (WHITE)
 アクチュエータ：ポリフェニレンスルファイド(PPS)、ガラス充填、UL94V-0、黒
 ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
 ターミナル：リン青銅、(t=0.2)
 TERMINAL: PHOSPHOR BRONZE
 金具：リン青銅、(t=0.2)
 FITTING NAIL: PHOSPHOR BRONZE
 2. 処理
 PLATING
 ターミナル TERMINAL
 鍍銀ビスマスめっき(1.0 μm 以上)
 下地：ニックルめっき(1.0 μm 以上)
 TIN SILVER BISMUTH PLATING (1.0 MICROMETER MINIMUM)
 UNDER PLATING: NICKEL PLATING (1.0 MICROMETER MINIMUM)
 金具 FITTING NAIL
 鍍めっき(1.0 μm 以上)
 下地：ニックルめっき(1.0 μm 以上)
 TIN PLATING (1.0 MICROMETER MINIMUM)
 UNDER PLATING: NICKEL PLATING (1.0 MICROMETER MINIMUM)
 3. エンゲータ押付け時又は、アクチュエータがロックした状態になります。
 IN THE PACKAGE, ACTUATOR SHOULD BE LOCKED.
 4. 両面板に適用
 APPLY FOR EVEN CIRCUIT.
 5. フィッティングナイルを防止する金具
 FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.
 6. R0.3は、FPCの隅部域にのみ適用すること
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.
 7. ナチュラル方向の寸法寸法、及び金具半田付け面のずれ量は、基準値 [H] に対し上方0.1 MAX、下方0.15 MAXとする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM [H] UPPER DIRECTION 0.1 MAX., LOWER DIRECTION 0.15 MAX.
 8. ELVとR0HS適合品
 ELV AND R0HS COMPLIANT.

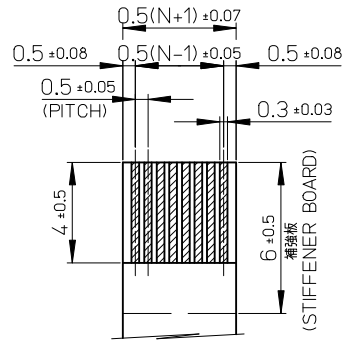
16.1	14.3	10.65	9.5	52745-2033	20
15.6	13.8	10.15	9	52745-1933	19
15.1	13.3	9.65	8.5	52745-1833	18
14.6	12.8	9.15	8	52745-1733	17
14.1	12.3	8.65	7.5	52745-1633	16
13.6	11.8	8.15	7	52745-1533	15
13.1	11.3	7.65	6.5	52745-1433	14
12.6	10.8	7.15	6	52745-1333	13
12.1	10.3	6.65	5.5	52745-1233	12
11.6	9.8	6.15	5	52745-1133	11
11.1	9.3	5.65	4.5	52745-1033	10
10.6	8.8	5.15	4	52745-0933	9
10.1	8.3	4.65	3.5	52745-0833	8
9.6	7.8	4.15	3	52745-0733	7
9.1	7.3	3.65	2.5	52745-0633	6
8.1	6.3	2.65	1.5	52745-0433	4
D	C	B	(A)	EMBOSSD PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52745-**22

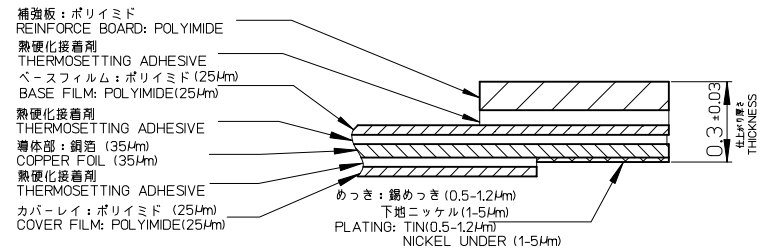
REVISED EC NO: J2013-1168 DRAWN:MSANJIMA CHK'D:KTAKAHASHI APPR:KMORIKAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY TMORISHITA	DATE 2012/09/06	TITLE 0.5MM FPC CONN ZIF R/A HOUSING ASSY (UPPER CONTACT) molex				
		10 OVER 30 UNDER	± 0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/07					
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15					
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-52745-055		1 OF 2			
A	REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



適合FPC推奨寸法
APPLICABLE FPC
PLATING RECOMMENDED DIMENSION
仕上がり厚さ: 0.3±0.03
THICKNESS: 0.3±0.03/-0.03



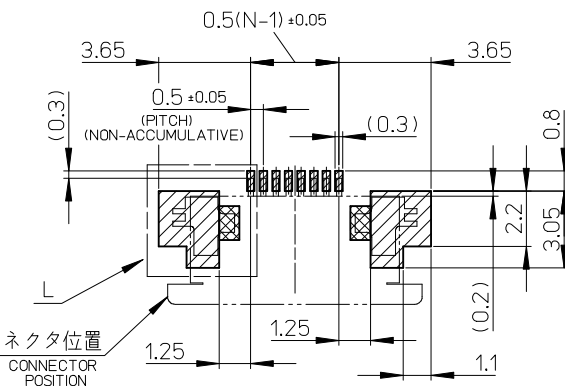
適合FFC推奨寸法
APPLICABLE FFC
PLATING RECOMMENDED DIMENSION
仕上がり厚さ: 0.3±0.03
THICKNESS: 0.3±0.03/-0.03



FPC構成推奨仕様
STRUCTURE OF FPC

FPCについて:
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様お願い致します。

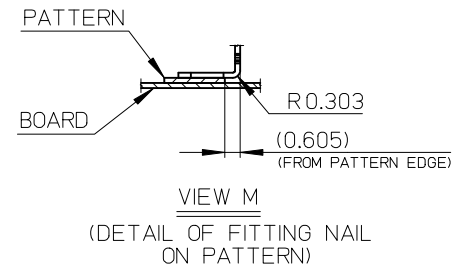
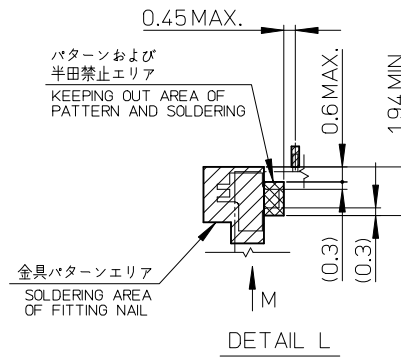
ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE
RECOMMENDED MATERIAL: STIFFENER FILM POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.



推奨基板レイアウト
(マウント面)

RECOMMENDED P.C BOARD
PATTERN DIMENSION
(MOUNTING SIDE)

マスク厚: 100 μm
マスク開口率: 100%
SCREEN THICKNESS: 100 μm
SCREEN OPEN TATIO: 100%



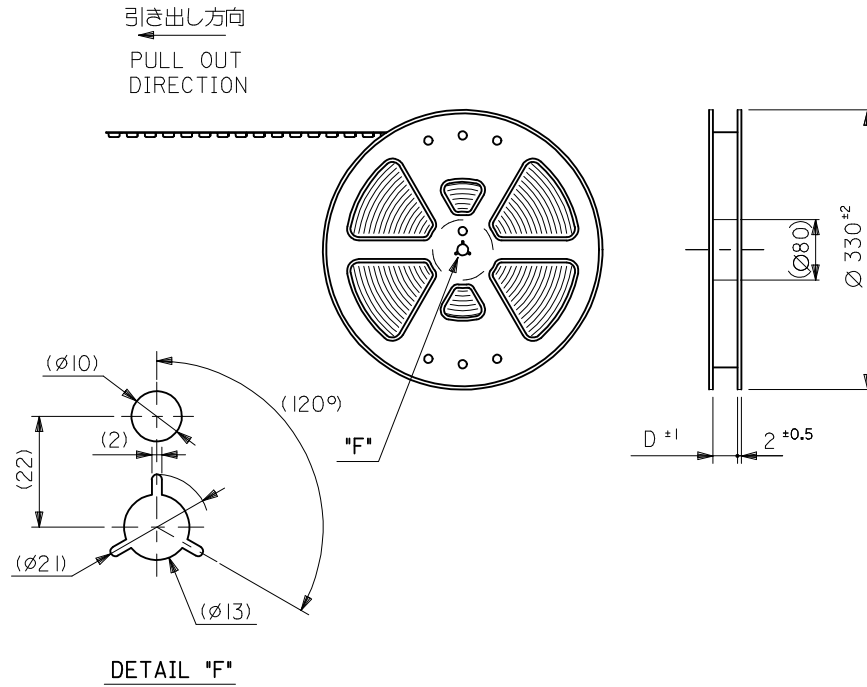
REVISED		DESCRIPTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
EC NO: J2013-1168	2013/03/15	DRWN:KONDO	2013/03/15	10 UNDER	±0.2	DRAWN BY	DATE	5:1	METRIC	0.5MM FPC CONN ZIF R/A HOUSING ASSY (UPPER CONTACT)	
CHKD:KAKAHASHI	2013/03/15	CHKD:KAKAHASHI	2013/03/15	10 OVER 30 UNDER	±0.25	CHECKED BY	DATE				
APPR:KMORIKAWA	2013/04/25	APPR:KMORIKAWA	2013/04/25	30 OVER	±0.3	APPROVED BY	DATE			molex	
				ANGULAR	±3 °	MATERIAL NO.					
A		REV		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ENTER PART		DOCUMENT NO.		SD-52745-055	
						SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			SHEET NO. 2 OF 2	

注記 NOTES

- 製品番号 52745-**-22の梱包状態はアクチュエータがロックした状態とする。
詳細寸法については図面SD-52745-055を参照下さい。
IN THE PACKAGE,ACTUATOR OF PART NO.52745-**-22 SHOULD BE LOCKED
RE DETAILED DIMENSIONS,SEE SD-52745-055
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

トップテープ リーダー部	トップテープ 未接着部
175 ±25	25 ±5
TOP TAPE LEADER PART	TOP TAPE NON-BONDED PART

引き出し方向 PULL OUT DIRECTION	リーダー部 (空部) LEADER PART (EMPTY)	部品挿入部 COMPONENT SUPPLIER	末端部 (空部) TAIL PART (EMPTY)
	120 ±20		150 ±40
- カバーテープの剥離強度については、IEC60286-3 に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.



5. 材料
 キャリアテープ：ポリプロピレン (PP)
 トップテープ：PET, PE, PEF
 リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
 TOP TAPE:PET,PE,PEF
 REEL:POLYSTYREN(PS)
 <RECYCLE MATERIAL CONTAINED>

6. ELV 及び RoHS 適合品
 ELV AND RoHS COMPLIANT

RELEASED EC NO: J2013-1014 DRWN:TMORISHITA 2012/09/05 CHKDK:KTAKAHASHI 2012/09/07 APPR:KMORIKAWA 2013/03/15	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY TMORISHITA	DATE 2012/09/05	TITLE EMBOSS TAPE PACKAGED FOR 0.5MM FPC CONN ZIF R/A HOUSING ASSY				
		10 OVER 30 UNDER	± 0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/07					
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15	molex				
		ANGULAR ±3 °		MATERIAL NO.						
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART			SD-52745-056			1 OF 3	
0	REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

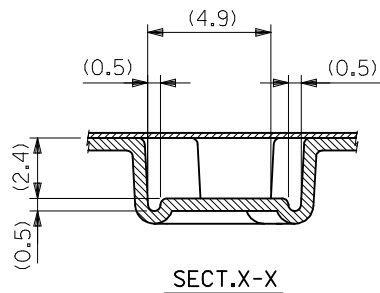
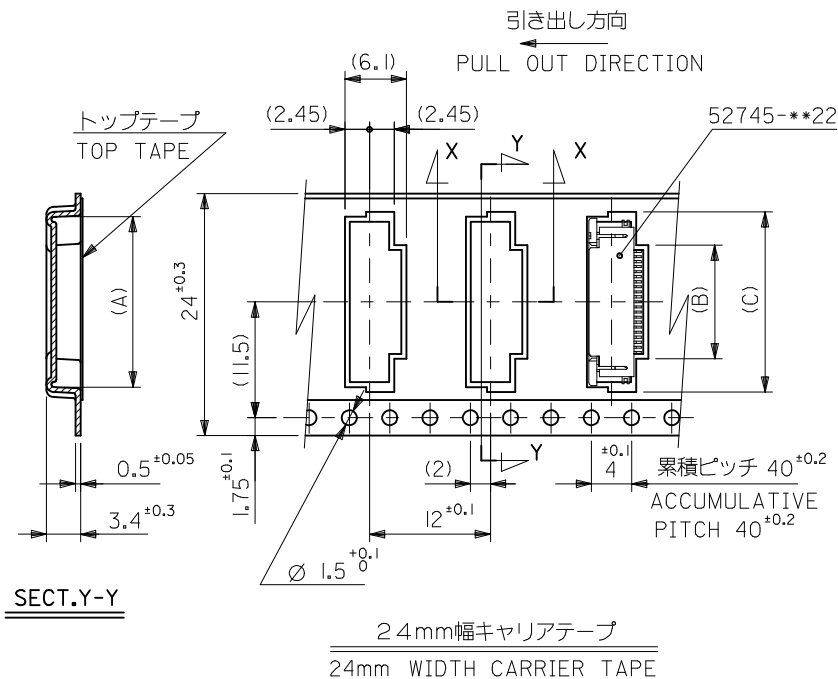
E

D

C

B

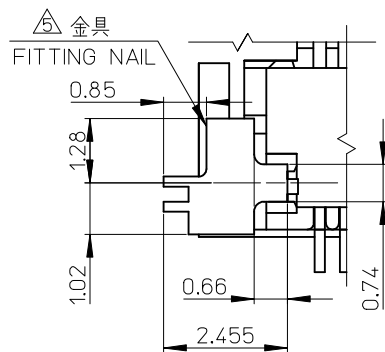
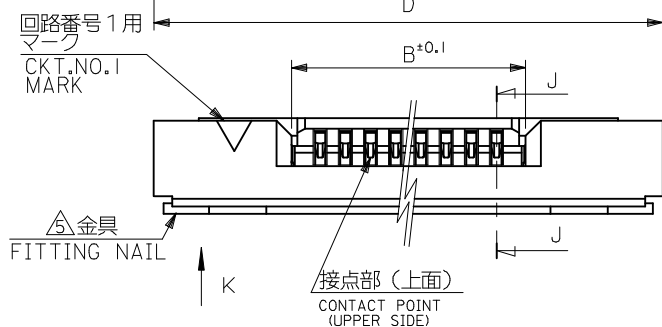
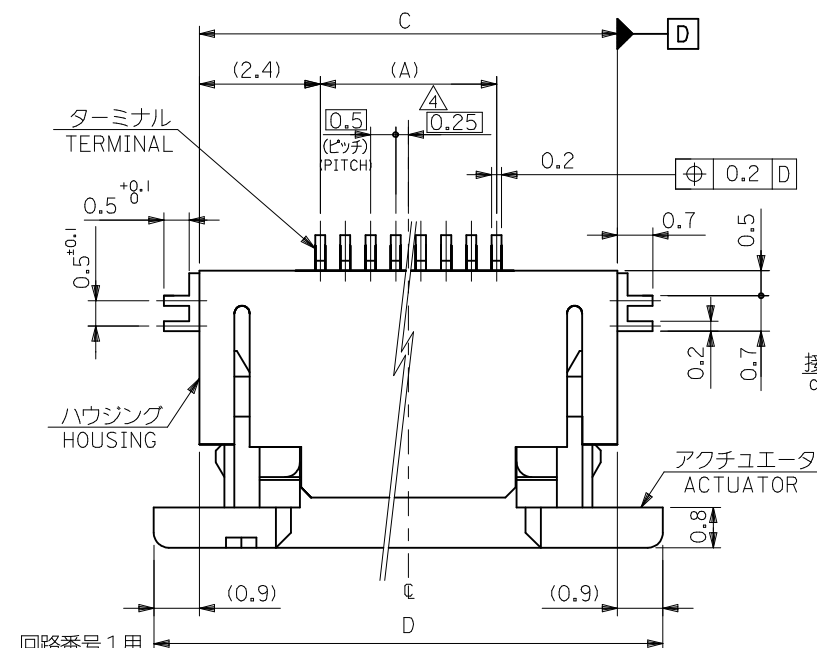
A



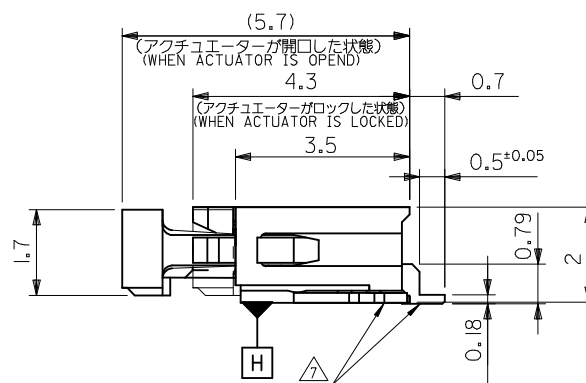
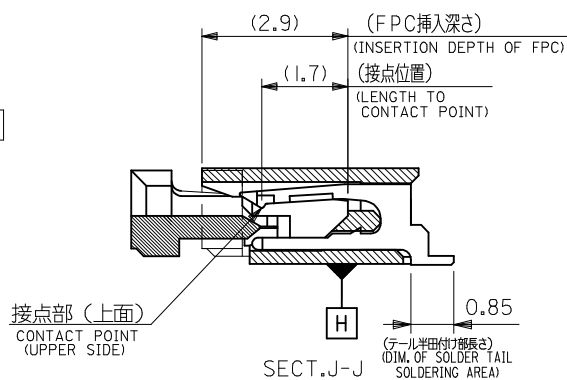
24	25.5	17.4	10.8	16.4	52745-2033	20
		16.9	10.3	15.9	└ - 1933	19
		16.4	9.8	15.4	└ - 1833	18
		15.9	9.3	14.9	└ - 1733	17
		15.4	8.8	14.4	└ - 1633	16
		14.9	8.3	13.9	└ - 1533	15
		14.4	7.8	13.4	└ - 1433	14
		13.9	7.3	12.9	└ - 1333	13
		13.4	6.8	12.4	└ - 1233	12
		12.9	6.3	11.9	└ - 1133	11
		12.4	5.8	11.4	└ - 1033	10
		11.9	5.3	10.9	└ - 0933	9
		11.4	4.8	10.4	└ - 0833	8
		10.9	4.3	9.9	└ - 0733	7
		10.4	3.8	9.4	52745-06 33	6
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CIRCUIT
CONNECTOR SERIES NO. : 52745-**22						

CONNECTOR SERIES NO. : 52745-**22

RELEASED EC NO.: J2013-1014 DRWN: TMORISHITA 2012/09/05 CHKD: TAKAHASHI 2012/09/07 APPR: KMORIKAWA 2013/03/15	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY TMORISHITA	DATE 2012/09/05	TITLE EMBOSS TAPE PACKAGED FOR 0.5MM FPC CONN ZIF R/A HOUSING ASSY				
		10 OVER 30 UNDER	± 0.25	CHECKED BY TAKAHASHI	DATE 2012/09/07					
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15	DOCUMENT NO. SD-52745-056				
		ANGULAR ±3 °		MATERIAL NO.						
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART							
0	REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



VIEW K
(金具部投影図)
(DETAIL OF FITTING NAIL)



1. 使用材料
 MATERIAL
 ハウジング：ポリアミド(PA)、ガラス充填、UL94V-0、ナチュラル(白)
 HOUSING: POLYAMIDE, GLASS FILLED, UL94V-0, NATURAL (WHITE)
 アクチュエータボディ：フッ素樹脂(PPS)、ガラス充填、UL94V-0、黒
 ACTUATOR BODY: FLUOROPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
 ターミナル：リン青銅、(t=0.2)
 TERMINAL: PHOSPHOR BRONZE
 金具：リン青銅、(t=0.2)
 FITTING NAIL: PHOSPHOR BRONZE
 2. 処理
 PLATING
 ターミナル
 鍍銀ビスマスめっき(1.0 μm 以上)
 下地：ニックルめっき(1.0 μm 以上)
 TIN SILVER BISMUTH PLATING (1.0 MICROMETER MINIMUM)
 UNDER PLATING: NICKEL PLATING (1.0 MICROMETER MINIMUM)
 金具 FITTING NAIL
 鍍めっき(1.0 μm 以上)
 下地：ニックルめっき(1.0 μm 以上)
 TIN PLATING (1.0 MICROMETER MINIMUM)
 UNDER PLATING: NICKEL PLATING (1.0 MICROMETER MINIMUM)
 3. エンゲータ押付け時、アクチュエータがロックした状態になります。
 IN THE PACKAGE, ACTUATOR SHOULD BE LOCKED.
 4. 両面テープを貼る
 APPLY FOR EVEN CURTAIN.
 5. フィットングナールを剥離防止のP.W.B.パターン。
 FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.
 6. R0.3は、FPCの隅隅部にかからないこと
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.
 7. ナール方向の寸法寸法、及び金具半田付け面のずれ量は、基準値 [H] に対し上方0.1 MAX、下方0.15 MAXとする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM [H] UPPER DIRECTION 0.1 MAX., LOWER DIRECTION 0.15 MAX.
 8. ELVとR0HS適合品
 ELV AND R0HS COMPLIANT.

16.1	14.3	10.65	9.5	52745-2033	20
15.6	13.8	10.15	9	52745-1933	19
15.1	13.3	9.65	8.5	52745-1833	18
14.6	12.8	9.15	8	52745-1733	17
14.1	12.3	8.65	7.5	52745-1633	16
13.6	11.8	8.15	7	52745-1533	15
13.1	11.3	7.65	6.5	52745-1433	14
12.6	10.8	7.15	6	52745-1333	13
12.1	10.3	6.65	5.5	52745-1233	12
11.6	9.8	6.15	5	52745-1133	11
11.1	9.3	5.65	4.5	52745-1033	10
10.6	8.8	5.15	4	52745-0933	9
10.1	8.3	4.65	3.5	52745-0833	8
9.6	7.8	4.15	3	52745-0733	7
9.1	7.3	3.65	2.5	52745-0633	6
8.1	6.3	2.65	1.5	52745-0433	4
D	C	B	(A)	EMBOSSD PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52745-**22

REVISED EC NO: J2013-1168 DRAWN:MSANJIMA CHK'D:KTAKAHASHI APPR:KMORIKAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY TMORISHITA	DATE 2012/09/06	TITLE 0.5MM FPC CONN ZIF R/A HOUSING ASSY (UPPER CONTACT) molex				
		10 OVER 30 UNDER	± 0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/07					
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15					
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-52745-055		1 OF 2			
REV A				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					